

**Notice of References Cited**

Application/Control No.

09/896,093

Applicant(s)/Patent Under

Reexamination

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Examiner

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Art Unit

2823

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,258,710	07-2001	Rathore et al.	438/628
	B	US-5,391,517	02-1995	Gelatos et al.	438/643
	C	US-			
	D	US-			
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	I	US-			
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	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Wang et al., "Binary Cu-alloy layers for Cu-interconnections reliability improvement" IEEE International Proceedings on Interconnect Technology Conference, 4-6 June 2001, pp 86-88
	V	Nogami et al., "Characterization of the Cu/Barrier Metal Interface for Copper interconnects", IEEE International Proceedings on Interconnect Technology Conference, 1-3 June 1998, pp 298-300
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.